

5.0mm x 5.0mm FULL-COLOR SURFACE MOUNT LED LAMP

PRELIMINARY SPEC



ATTENTION

OBSERVE PRECAUTIONS FOR HANDLING **ELECTROSTATIC** DISCHARGE SENSITIVE **DEVICES**

Part Number: AAAF5051-02

Blue

Reddish-Orange

Green

Features

- CHIPS CAN BE CONTROLLED SEPARATELY.
- SUITABLE FOR ALL SMT ASSEMBLY AND SOLDER PROCESS.
- AVAILABLE ON TAPE AND REEL.
- WHITE SMD PACKAGE, SILICONE RESIN.
- PACKAGE: 500PCS / REEL.
- MOISTURE SENSITIVITY LEVEL: LEVEL 3.
- RoHS COMPLIANT.

Description

The Blue source color devices are made with InGaAIN Vertical Light Emitting Diode.

This devices are made with AlGaInP.

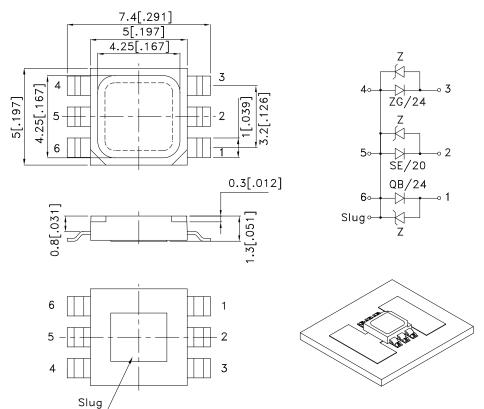
The Green source color devices are made with InGaAIN Vertical Light Emitting Diode.

Static electricity and surge damage the LEDS.

It is recommended to use a wrist band or anti-electrostatic glove when handling the LEDs.

All devices, equipment and machinery must be electrically grounded.

Package Dimensions



- 1. All dimensions are in millimeters (inches).
- 2. Tolerance is ±0.15[±0.006]unless otherwise noted.
- 3. Specifications are subject to change without notice.4. The device has a single mounting surface. The device must be mounted according to the specifications.





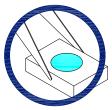
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Handling Precautions

Compare to epoxy encapsulant that is hard and brittle, silicone is softer and flexible. Although its characteristic significantly reduces thermal stress, it is more susceptible to damage by external mechanical force.

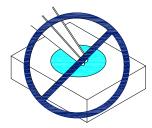
As a result, special handling precautions need to be observed during assembly using silicone encapsulated LED products. Failure to comply might leads to damage and premature failure of the LED.

1. Handle the component along the side surfaces by using forceps or appropriate tools.

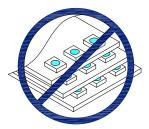


2. Do not directly touch or handle the silicone lens surface. It may damage the internal circuitry.

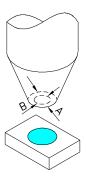




3. Do not stack together assembled PCBs containing exposed LEDs. Outside impact may scratch the silicone lens or damage the internal circuitry.



- 4. The outer diameter of the SMD pickup nozzle should not exceed the size of the LED to prevent air leaks. The inner diameter of the nozzle should be as large as possible.
- 5. A pliable material is suggested for the nozzle tip to avoid scratching or damaging the LED surface during pickup.
- 6. The dimensions of the component must be accurately programmed in the pick-and-place machine to insure precise pickup and avoid damage during production.



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Selection Guide

Part No.	Dice	Lens Type	lv (mcd) [2] @ 120mA		Фv (mlm) [2] @ 120mA		Viewing Angle [1]
			Min.	Тур.	Min.	Тур.	201/2
AAAF5051-02	Blue (InGaAlN)		1200	1450	5000	6300	120°
	Reddish-Orange (AlGaInP)	WATER CLEAR	2500	3100	8000	9000	
	Green (InGaAIN)		3800	4900	12500	17000	

- Notes: 1. θ 1/2 is the angle from optical centerline where the luminous intensity is 1/2 the optical centerline value. 2. Luminous intensity/ luminous Flux: +/-15%.

Electrical / Optical Characteristics at TA=25°C

Parameter	Symbol	Device	Value	Unit	
Power dissipation		Blue	0.432	w	
	Pt	Reddish-Orange	0.336		
		Green	0.444		
Junction temperature		Blue	110	°C	
	TJ	Reddish-Orange	110		
		Green	110		
Operating Temperature		Blue		°C	
	Тор	Reddish-Orange	-40 To +85		
		Green			
Storage Temperature	Tstg	Blue		°C	
		Reddish-Orange	-40 To +85		
		Green			
DC Forward Current [1]		Blue	120		
	lF	Reddish-Orange	120	mA	
		Green	120		
Peak Forward Current [2]		Blue	300		
	Iғм	Reddish-Orange	300	mA	
		Green	300		
Thermal resistance	Rth j-a	Blue	220	°C/W	
		Reddish-Orange	270		
		Green	200		
Electrostatic Discharge Threshold (HBM)		Blue		V	
		Reddish-Orange	8000		
		Green			

Notes:

- 1. Results from mounting on PC board FR4(pad size $\geq 100 \text{mm}^2$), mounted on pc board-metal core PCB is recommend for lowest thermal resistance.
- 2. 1/10 Duty Cycle, 0.1ms Pulse Width.

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Electrical / Optical Characteristics at T_A=25°C

	Symbol	Device	Value			
Parameter			Min.	Тур.	Max.	Unit
Wavelength at peak emission Ir=120mA		Blue		450		nm
	λ peak	Reddish-Orange		633		
		Green		515		
Dominant Wavelength Ir=120mA		Blue		457		nm
	λ dom [1]	Reddish-Orange		624		
		Green		525		
Spectral Line Half-width Ir=120mA		Blue		20		nm
	Δλ1/2	Reddish-Orange		30		
		Green		30		
Forward Voltage IF=120mA		Blue	2.6	3.1	3.6	٧
	VF [2]	Reddish-Orange	1.8	2.3	2.8	
		Green	2.6	3.2	3.7	
Temperature coefficient of λ peak IF=120mA, -10 $^{\circ}$ C \leq T \leq 100 $^{\circ}$ C		Blue		0.12		nm/° C
	TC λ peak	Reddish-Orange		0.09		
		Green		0.13		
Temperature coefficient of λ dom IF=120mA, -10 $^{\circ}$ C \leq T \leq 100 $^{\circ}$ C	TC λ dom	Blue		0.1		nm/° C
		Reddish-Orange		0.03		
		Green		0.11		
	TCv	Blue		-2.3		mV/° C
Temperature coefficient of VF IF=120mA, -10 $^{\circ}$ C \leq T \leq 100 $^{\circ}$ C		Reddish-Orange		-2.7		
, , , , , , , , ,		Green		-3.9		

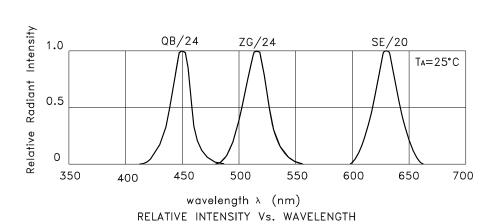
Notes:

1.Wavelength: +/-1nm.

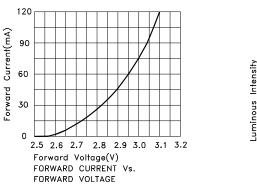
2. Forward Voltage: +/-0.1V.

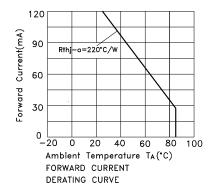
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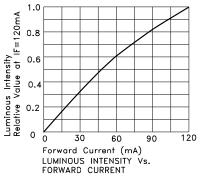
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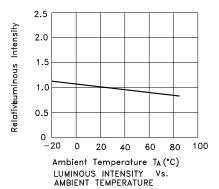


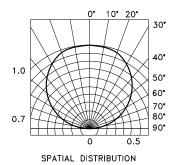
AAAF5051-02 Blue







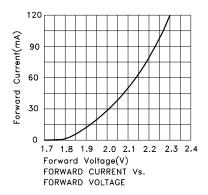


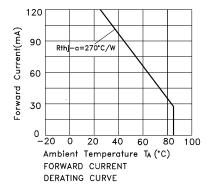


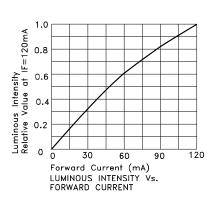
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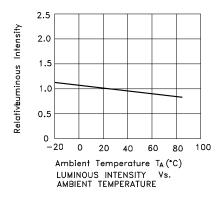
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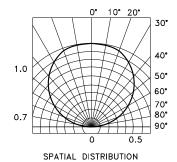
Reddish-Orange







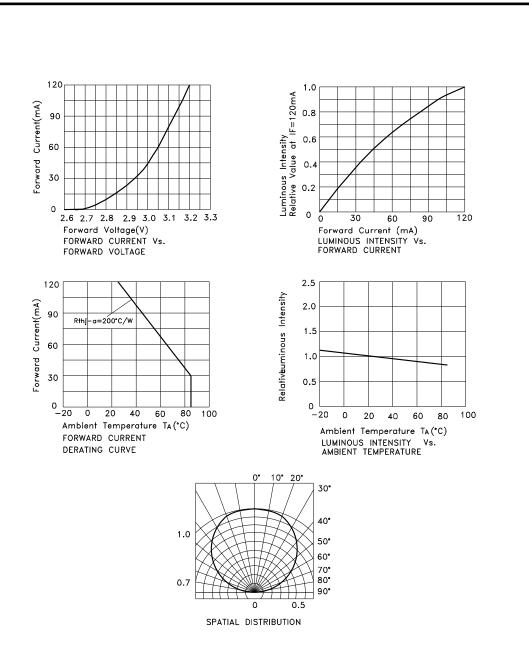




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Green

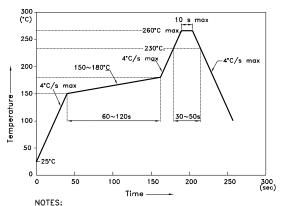


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Reflow Soldering Profile For Lead-free SMT Process.

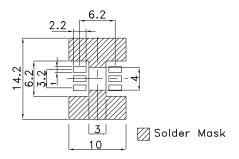


- NOTES:

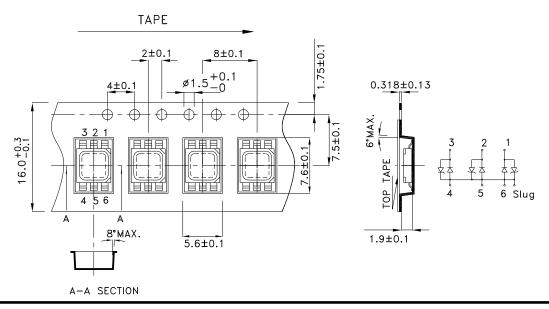
 1.We recommend the reflow temperature 245°C(+/-5°C). The maximum soldering temperature should be limited to 260°C.

 2.Don't cause stress to the epoxy resin while it is exposed to high temperature.
 - 3. Number of reflow process shall be 2 times or less.

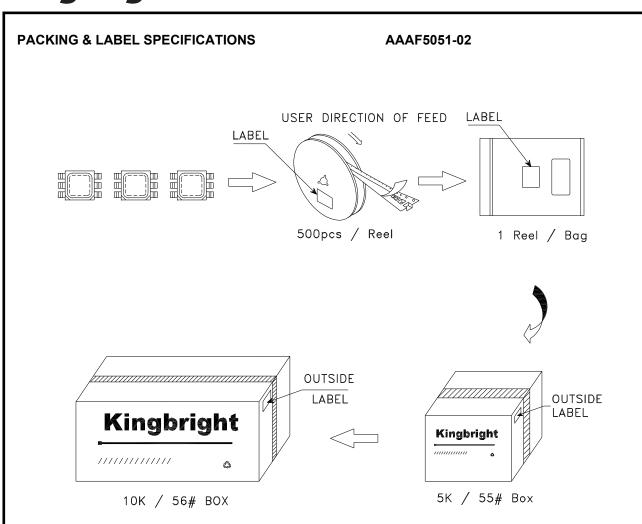
Recommended Soldering Pattern (Units: mm; Tolerance: ± 0.1)

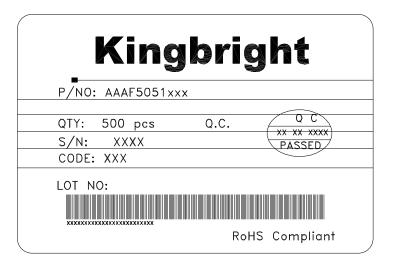


Tape Specifications (Units : mm)



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